



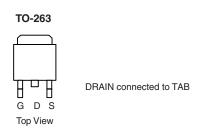
N-Channel 55-V (D-S), 175 °C MOSFET, Logic Level

PRODUCT SUMMARY			
V _{(BR)DSS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)	
55	0.019 at V _{GS} = 10 V	40	
	0.025 at V _{GS} = 4.5 V	35	

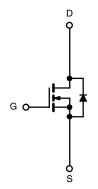
FEATURES

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature





Ordering Information: SUM40N05-19L-E3 (Lead (Pb)-free)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _C = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	55	V	
Gate-Source Voltage		V _{GS}	± 20		
Continuous Drain Current (T _{.I} = 175 °C)	T _C = 25 °C	I _D	40	Δ.	
Continuous Diam Current (1j = 173 G)	T _C = 100 °C		28		
Pulsed Drain Current		I _{DM}	80	A	
Avalanche Current, Single Pulse		I _{AS}	30		
valanche Energy, Single Pulse L = 0.1 mH		E _{AS}	45	mJ	
Power Pitaliani	T _C = 25 °C	P _D	65 ^a	W	
Power Dissipation	T _A = 25 °C ^c		3.1 ^b		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	(PCB Mount) ^b	R _{thJA}	40	°C/W	
Junction-to-Case		R _{thJC}	2.3	C/VV	

Notes:

- a. See SOA curve for voltage derating.
- b. Surface Mounted on FR4 board, $t \le 10 \text{ s.}$

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^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.

SUM40N05-19L

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			l				
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	55			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{DS} = 250 \mu\text{A}$	1.0	2.0	3.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current		V _{DS} = 55 V, V _{GS} = 0 V			1	μΑ	
	I _{DSS}	$V_{DS} = 55 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			50		
		$V_{DS} = 55 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 \text{ °C}$			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α	
Drain-Source On-State Resistance ^a		V _{GS} = 10 V, I _D = 20 A		0.0155	0.019		
	r · ·	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 125 ^{\circ}\text{C}$			0.033		
	r _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 175 ^{\circ}\text{C}$			0.040	Ω	
		$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.020	0.025		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		50		S	
Dynamic ^b							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		885		pF	
Output Capacitance	C _{oss}			185			
Reverse Transfer Capacitance	C _{rss}			80			
Total Gate Charge ^c	Qg			10.5	13	nC	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 25 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 35 \text{ A}$		4			
Gate-Drain Charge ^c	Q_{gd}			4.8			
Gate Resistance	R _g	f = 1.0 MHz		5.0		Ω	
Turn-On Delay Time ^c	t _{d(on)}			5	8		
Rise Time ^c	t _r	V_{DD} = 25 V, R_L = 0.3 Ω I_D \cong 35 A, V_{GEN} = 10 V, R_G = 2.5 Ω		18	30	ns	
Turn-Off Delay Time ^c	t _{d(off)}			20	30		
Fall Time ^c	t _f			100	150		
Source-Drain Diode Ratings and Cha	aracteristics T	_C = 25 °C ^b	I				
Continuous Current	I _S				35		
Pulsed Current	I _{SM}				80	A	
Forward Voltage ^a	V_{SD}	I _F = 35 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}	25		25	40	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 35 A, di/dt = 100 A/μs		1.5	2.5	Α	
Reverse Recovery Charge	Q _{rr}			0.019	0.05	μС	

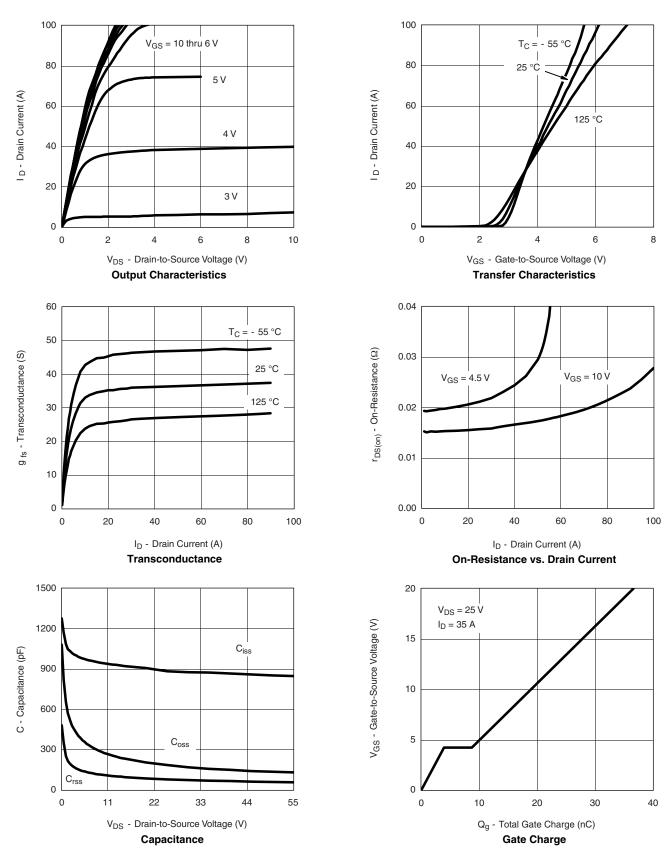
Notes

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



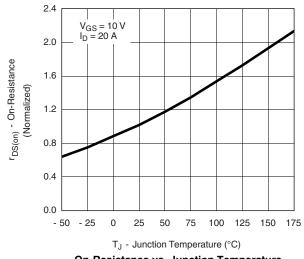
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

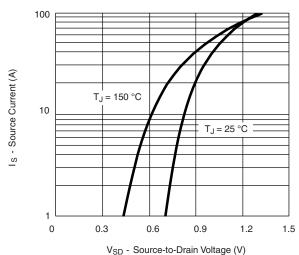


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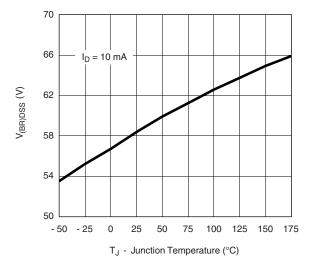
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On-Resistance vs. Junction Temperature

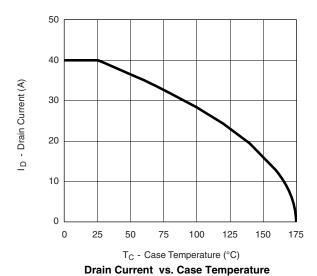
Source-Drain Diode Forward Voltage

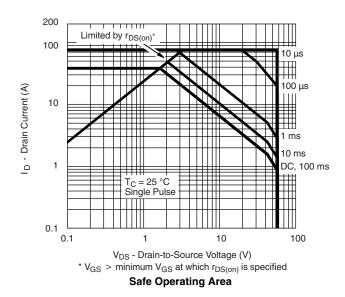


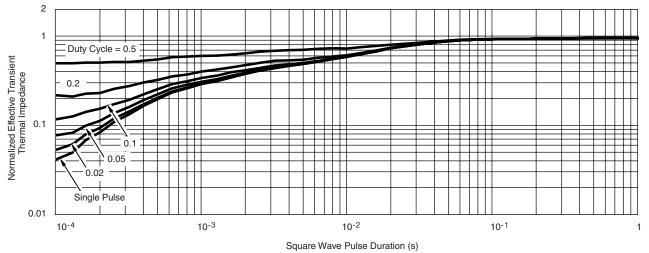
Drain Source Breakdown vs. **Junction Temperature**



THERMAL RATINGS







Normalized Thermal Transient Impedance, Junction-to-Case

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